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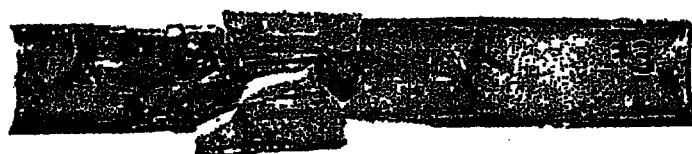
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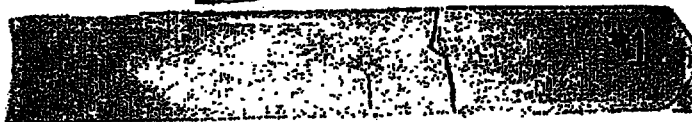
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(54) Title: CURABLE RESIN COMPOSITION, METHOD FOR THE PREPARATION THEREOF, AND ARTICLES DERIVED THEREFROM



UPR Neat



UPR + 4% PVA



UPR + 4%
Unsat.-PPE

← 250 mm →

(57) Abstract: A curable resin composition includes an unsaturated polyester, an alkenyl aromatic compound, and a capped poly(arylene ether). The composition is suitable for low temperature curing and exhibits reduced curing shrinkage and reduced brittleness.

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